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Applicant: Salman Akram ✓

Serial No.: 09/853,111 ✓

Filed: May 10, 2001 ✓

For: Method of Fabricating Mounted
Multiple Semiconductor Dies In
A Package (As Amended)

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Group A

Examiner:

A. Chambliss

Atty. Dkt. No.:

MCT.0012D1US
(97-0141)

A. Chambliss
#10
1/28/03

Commissioner for Patents
Washington DC 20231

SUPPLEMENTAL RESPONSE

Sir:

In response to the notice of incomplete response, please amend the above-referenced patent application as follows:

Date of Deposit: 01-03-03

I hereby certify under 37 CFR 1.8(a) that this correspondence is being deposited with the United States Postal Service as **first class mail** with sufficient postage on the date indicated above and is addressed to the Commissioner for Patents, Washington DC 20231.

Cynthia L. Hayden